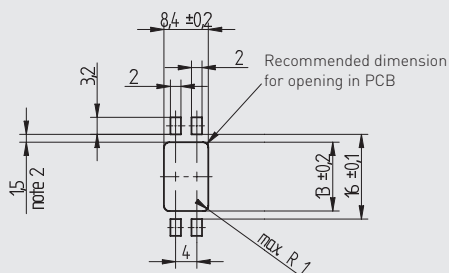


Note 1: Maximum thickness of PCB and luminaire heat sink shall not exceed 3.6 mm.

General note: It is recommended to make an electrical connection between both poles of each polarity on the solder pad.



Note 2: The minimum creepage distance has to be guaranteed, depends on the application.

pkg. wt. part no.
500 0.5 g 46.112.1001.50

SMD-Push through terminal block with push wire contacts

2 pole

Direct insertion of solid and stranded, tinned wire ends

Wires can be released by twisting and pulling the wire simultaneously.

Mounting and wiring position: PCB bottom side

Ballast and PCB terminal block on one level

Machine-compatible "tape-and-reel" packaging

Fixing: Lead-free reflow soldering according to DIN EN 610760-1, section 6

Material: Housing: PPA, white
Contact material: CuNi
Contact surface: hot-dip tinned 5-10 µm

LEP-LINE	U_{imp} 2,5 kV		$0.2 - 0.75mm^2$ AWG 24-18	$0.2 - 0.5mm^2$ AWG 24-20	$8 \pm 1mm$	CAD
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SMD-Push through terminal block
General technical information

Connection data	
Connection technology	Push wire contacts
Solid wires	0.2 - 0.75 mm ² , AWG 24-18
Stranded, tinned wires	0.2 - 0.5 mm ² , AWG 24-20
Strip length	8 +1 mm
Conductor entry angle to the PCB	0 - 10°
Wire release function by	Twisting and Pulling

Pull-out force according to DN 60999-1	
0.2 mm ²	min. 10 N
0.34 mm ²	min. 15 N
0.5 mm ²	min. 20 N
0.75 mm ²	min. 30 N
Insertion force	max. 10 N

Geometrical data	
Pin spacing	4 mm / 0.157 inch
Width	7.95 mm / 0.31 inch
Height	7.5 mm / 0.295 inch
Depth	21.7 mm / 0.85 inch
Reel diameter of tape-and-reel packaging	330 mm (13")
Reel width	32 mm
Pitch distance	16 mm
Packaging unit tape-and-Reel	500
Packaging unit cardboard	5.000 (10 reels)

Material data	
Insulating material group	I
Insulating material	PPA, white
PTI	600
Flammability class, based on UL UL 94	V0
Contact material	CuNi
Contact surface	hot-dipped tinned 5-10 µm

Mechanical data	
Mounting position	PCB bottom side
Mounting type	Lead-free reflow soldering

Temperature data	
Marginal temperatures	-40 °C to + 150 °C
Ambient temperature	-40 °C to + 125 °C
T-classification according to IEC 60998-1 para. 12	120°

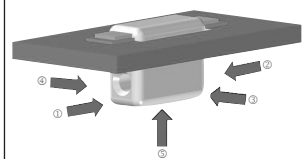
Rated data according to IEC / EN 60947-7-4 (IEC/EN 60664-1) für Leiterplattentyp FR4 1.0 mm	
Rated voltage (III / 3)	200 V
Rated impulse voltage (III / 3)	2.5 kV
Rated voltage (III / 2)	250 V
Rated impulse voltage (III / 2)	2.5 kV
Rated voltage (II / 2)	400 V
Rated impulse voltage (II / 2)	2.5 kV
Rated current	9 A

Rated data according to IEC / EN 60947-7-4 (IEC/EN 60664-1) für Leiterplattentyp IMS	
Rated voltage (III / 3)	63 V
Rated impulse voltage (III / 3)	2.5 kV
Rated voltage (III / 2)	160 V
Rated impulse voltage (III / 2)	2.5 kV
Rated voltage (II / 2)	320 V
Rated impulse voltage (II / 2)	2.5 kV
Rated current	9 A

Rated data according to UL 1977	
Rated voltage UL 1977	300 V
Rated current UL 1977	9 A

Country specific certificates	
VDE ENEC	EN 60947
UL	cURus, File No. E-365006

Shear forces according to DIN 62137-1-2 in [N]	
Direction 1 +2 shear force along	-
Direction 3 + 4 shear force across	-
Direction 5 pull-off force	>30

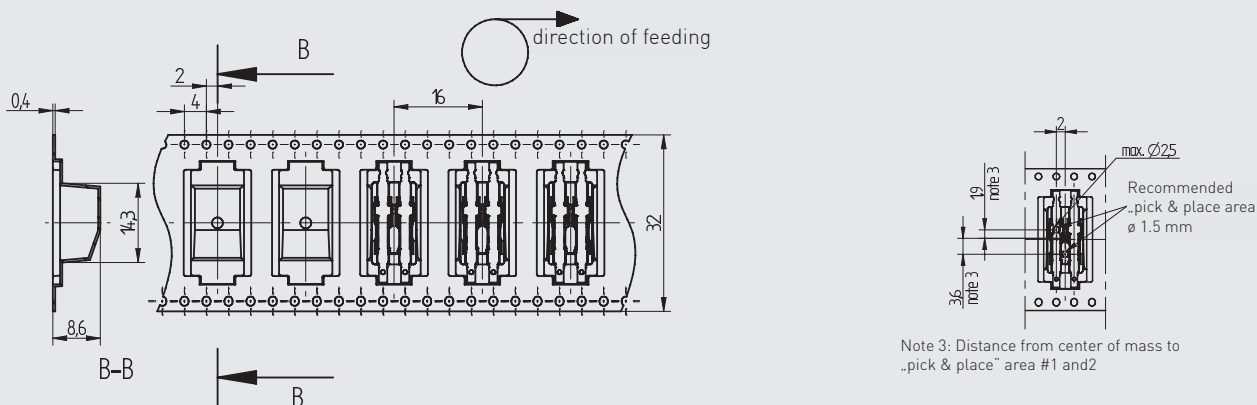




Instructions for soldering process

Suitable for leadfree-reflow-profiles according to DIN EN 61760-1 respective DIN EN 60068-2-58 up to peak-temperature of max. 260°C. Due to different application-specific parameters (component arrangement and alignment, soldering system, solder paste), it is recommended to use test runs to determine a suitable profile under production conditions.

Depending on the SMD soldering process and associated parameters a minor discoloration might occur. However, this will not influence the functionality.



Note 3: Distance from center of mass to „pick & place“ area #1 and2

Storage time	Solderability up to 6 months when stored between -5°C and +40°C and rel. humidity between 10...60% r H. After a storage time of 6 months, solderability has to be checked according to J-STD-002D or DIN EN 60068-2-58:2016.
max. allowed number of reflow-processes	3
Reflow-profile	<p>Reflow-profile (lead-free)</p>
Solderability	Solderability of components is checked by wetting test according to J-STD-002D
Assembly method	SMD, according to drawing
Recommended solder stencil thickness	100 - 150 µm (recommendation BJB 150)